

EAST

10 | 654,082

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	560464	((IC OR integrated ADJ3 circuit) OR substrate OR wafer) WITH (process\$3 OR produc\$4 OR fabrication)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:19
S2	48229	(radiation OR radiating) WITH apparatus	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:20
S3	174344	radiation WITH (emit\$4 OR produc\$3 OR exposure OR expos\$3)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:22
S4	14638	S2 WITH S3	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:22
S5	618	S1 SAME S4	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:23
S6	1447	S1 WITH exposure WITH (radiation OR radiat\$3)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:23
S7	10	S6 WITH damag\$3	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:25
S8	31	S6 WITH measur\$4	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:27
S9	79	700/123.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:27
S10	541	438/57.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:27
S11	128	427/492.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:28
S12	422	427/496.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:28
S13	847	427/508.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:28
S14	340	427/521.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:29
S15	0	S6 AND S9	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:29
S16	0	S6 AND S10	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:29

S17	3	S6 AND S11	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:30
S18	8	S6 AND S12	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:30
S19	10	S6 AND S13	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:31
S20	5	S6 AND S14	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 11:59
S21	3118	707/102.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:19
S22	252	((production OR manufacturing) WITH (system OR method OR process)) AND S21	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:21
S23	252	((production OR manufacturing) WITH (system OR method OR process)) AND S21	US-PGPUB; USPAT	OR	OFF	2005/07/28 15:22
S24	162	(compiling OR accessing OR editing) AND S22	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:40
S25	2102	(optimization OR optimizing) WITH database	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:41
S26	59	((production OR manufacturing) WITH (system OR method OR process)) SAME S25	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 15:42
S27	3	S25 WITH (inspection WITH system)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 17:08
S28	48229	(radiation OR radiating) WITH apparatus	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 17:08
S29	117	S28 WITH (inspection WITH system)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:07
S30	560464	((IC OR integrated ADJ3 circuit) OR substrate OR wafer) WITH (process\$3 OR produc\$4 OR fabrication)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 17:09
S31	1447	S30 WITH exposure WITH (radiation OR radiat\$3)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 17:09
S32	0	S31 WITH (inspection WITH system)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 17:10
S33	0	S31 SAME S25	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 17:11

S34	0	S31 AND S25	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/28 17:11
S35	48229	(radiation OR radiating) WITH apparatus	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:08
S36	560467	((IC OR integrated ADJ3 circuit) OR substrate OR wafer) WITH (process\$3 OR produc\$4 OR fabrication)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:08
S37	1447	S36 WITH exposure WITH (radiation OR radiat\$3)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:08
S38	0	(S35 WITH (inspection WITH system)) SAME S37	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:09
S39	223	S37 WITH ((inspection WITH system) OR ((radiation OR radiating OR radiate) WITH (apparatus OR machine OR device OR unit)))	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:12
S40	33	(S37 WITH ((inspection WITH system) OR ((radiation OR radiating OR radiate) WITH (apparatus OR machine OR device OR unit))))).ab.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:23
S41	541	438/57.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:14
S42	128	427/492.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:14
S43	422	427/496.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:14
S44	1084	S41 OR S42 OR S43	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:14
S45	1	S39 AND S44	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:15
S46	3	("5043548" "5609687" "5723176").PN. OR ("6736898"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/07/29 10:16
S47	10906	((radiation OR radiating OR radiate) WITH (apparatus OR machine OR device OR unit)) WITH (IC OR (integrated WITH circuit) OR substrate OR wafer)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:25
S48	69148	(radiation OR radiating OR radiate) WITH (laser OR lamp)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:24

S49	1217	S47 WITH S48	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:24
S50	5844	(expose OR exposure) WITH (substrate OR wafer OR IC) WITH radiation	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 10:26
S51	46	S49 SAME S50	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:11
S52	1	"6788404".pn	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:13
S53	51	("4935278" "5995370" "4476563" "4546983" "4772784" "4790893" "4918749" "4929485" "4941146" "4968370" "5013635" "5206114" "5224195" "5335213" "5414427" "5418382" "5570122" "5619369" "5838590" "5900616" "5940314" "6056434" "6072855" "6208791" "6326636" "6359678" "4329687" "5024927" "5790922" "4960734" "5315482" "5393577" "5569569" "5699319" "3832948" "4046986" "4323842" "4522482" "4538252" "4812346" "4975358" "4979149" "6475753" "5565875" "5576718" "5695670" "6080965" "4618865" "4757232" "4759948").pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/07/29 11:13